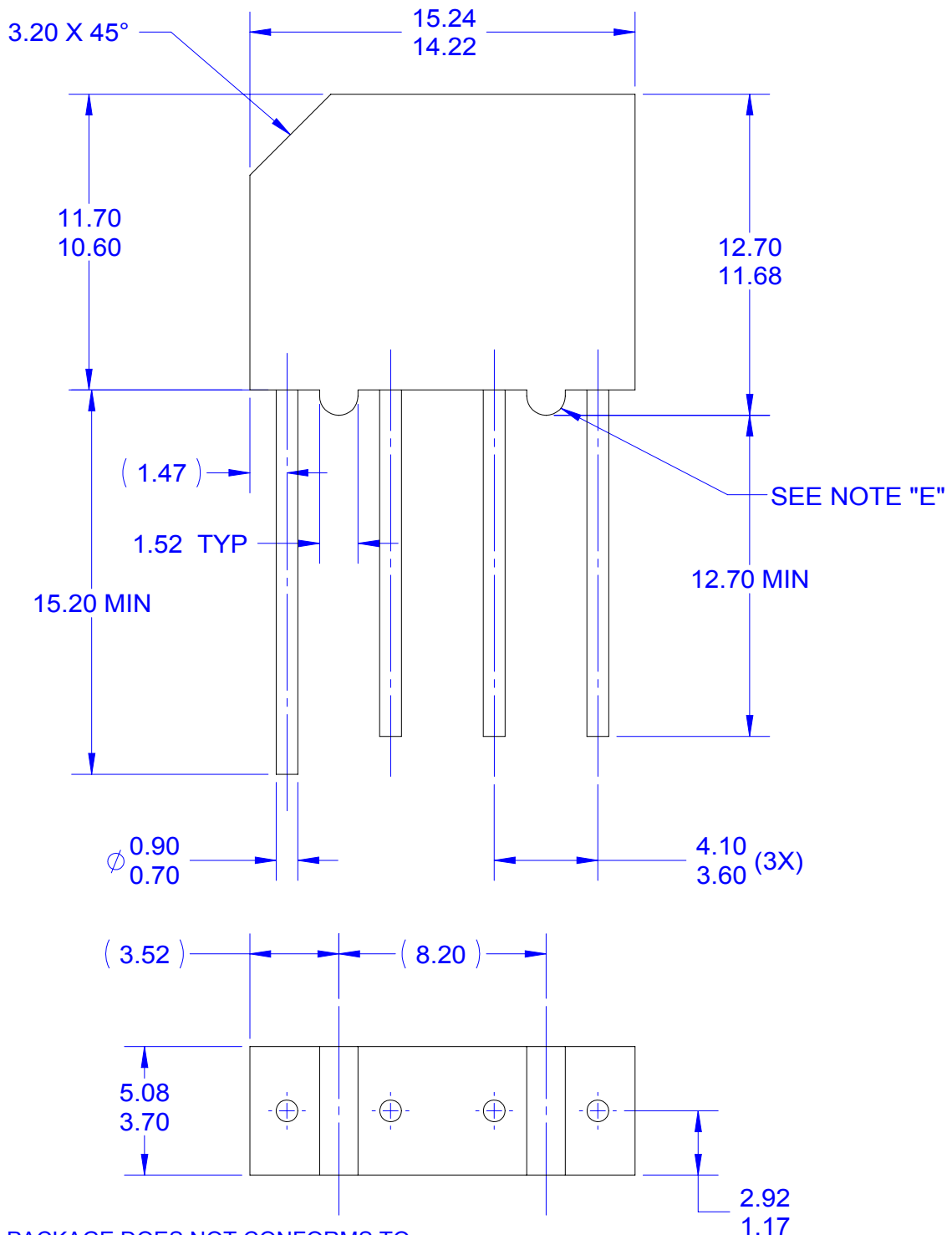


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NOTES:

- A. THIS PACKAGE DOES NOT CONFORMS TO ANY STANDARD.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- E. THIS PACKAGE PROTRUSION IS OPTIONAL.
- F. DRAWING FILE NAME: KBPM04AREV2

APPROVALS		DATE			
DRAWN: BOBOY MALDO		11FEB10			
CHECKED: BENJO ROLUNA					
APPROVED: G CHEW					
APPROVED: HOWARD ALLEN				4LD, KBPM, THROUGH-HOLE, MOLDED PACKAGE	
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		1:1	N/A	MKT-KBPM04A	2
FORMERLY: N/A				SHEET: 1 OF 1	